

Day : Thursday
 Date: 5/18/2006
 Time: 11:40:01


PALM INTRANET

Inventor Information for 10/710562

Inventor Name	City	State/Country
DAUBENSPECK, TIMOTHY H.	COLCHESTER	VERMONT
GAMBINO, JEFFREY P.	WESTFORD	VERMONT
MUZZY, CHRISTOPHER D.	BURLINGTON	VERMONT
SAUTER, WOLFGANG	RICHMOND	VERMONT

[Appln Info](#) [Contents](#) [Petition Info](#) [Atty/Agent Info](#) [Continuity Data](#) [Foreign Data](#) [Inventors](#)

Search Another: Application# or Patent#

PCT / / or PG PUBS #

Attorney Docket #

Bar Code #

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | Home page

US 20060197228 A1	20060907	SINGLE MASK PROCESS FOR VARIABLE THICKNESS DUAL DAMASCENE STRUCTURES, OTHER GREY- MASKING PROCESSES, AND STRUCTURES MADE USING GREY-MASKING	257/773		Daubenspeck; Timothy Harrison et al.
US 20060189007 A1	20060824	WIREBOND CRACK SENSOR FOR LOW-K DIE	438/14	438/17	Aoki; Toyohiro et al.
US 20060151851 A1	20060713	ON-PAD BROADBAND MATCHING NETWORK	257/531	257/536	Pillai; Edward R. et al.
US 20060145291 A1	20060706	Structure and programming of laser fuse	257/529		Badami; Dinesh A. et al.
US 20060110851 A1	20060525	Methods for forming co-planar wafer-scale chip packages	438/108	438/125	Burrell; Lloyd G. et al.
US 20060099775 A1	20060511	Crack stop for low K dielectrics	438/465	257/E21.251; 257/E21.309; 257/E21.599; 438/460; 438/462	Daubenspeck; Timothy H. et al.
US 20060087035 A1	20060427	SOLDER WALL STRUCTURE IN FLIP-CHIP TECHNOLOGIES	257/737		Daubenspeck; Timothy H. et al.
US 20060081981 A1	20060420	Method of forming a bond pad on an I/C chip and resulting structure	257/734	257/750; 257/766; 257/E23.02; 438/614; 438/652	Biggs; Julie C. et al.
US 20060076677 A1	20060413	Resist sidewall spacer for C4 BLM undercut control	257/734		Daubenspeck; Timothy Harrison et al.

US 20060076159 A1	20060413	CONTOUR STRUCTURES TO HIGHLIGHT INSPECTION REGIONS	174/261	257/758	Daubenspeck; Timothy H. et al.
US 20060057831 A1	20060316	WIRE BOND PADS	438/612	438/613; 438/614	Daubenspeck; Timothy H. et al.
US 20060057822 A1	20060316	CHIP DICING	438/463		Daubenspeck; Timothy H. et al.
US 20060016861 A1	20060126	Damascene patterning of barrier layer metal for C4 solder bumps	228/180.21	228/180.22; 29/840	Daubenspeck; Timothy H. et al.
US 20050121803 A1	20050609	Internally reinforced bond pads	257/779	257/781; 257/E23.02; 438/612; 438/614	Angell, David et al.
US 20050104188 A1	20050519	OPTIMUM PADSET FOR WIRE BONDING RF TECHNOLOGIES WITH HIGH-Q INDUCTORS	257/690	257/E23.02; 438/612	Coolbaugh, Douglas D. et al.
US 20050101114 A1	20050512	Triple damascene fuse	438/601	257/529; 257/E23.149; 257/E23.167; 438/132	Daubenspeck, Timothy H. et al.
US 20050093091 A1	20050505	STRUCTURE AND PROGRAMMING OF LASER FUSE	257/529	257/E23.146; 257/E23.148; 257/E23.15; 438/333	Badami, Dinesh A. et al.
US 20050077593 A1	20050414	WIRING PROTECTION ELEMENT FOR LASER DELETED TUNGSTEN FUSE	257/529	257/E23.15	Motsiff, William T. et al.
US 20050062170 A1	20050324	Method of forming a bond pad on an I/C chip and resulting structure	257/780	257/784; 257/E23.02; 438/612; 438/617	Biggs, Julie C. et al.
US	20050303	METHOD OF	216/83	257/E21.304	Codding,

20050045591 A1		POLISHING C4 MOLYBDENUM MASKS TO REMOVE MOLYBDENUM PEAKS			Steven R. et al.
US 20050026397 A1	20050203	CRACK STOP FOR LOW K DIELECTRICS	438/465	257/E21.251; 257/E21.309; 438/460	Daubenspeck, Timothy H. et al.
US 20040195642 A1	20041007	Internally reinforced bond pads	257/459	257/E23.02	Angell, David et al.
US 20040099632 A1	20040527	Thinning of fuse passivation after C4 formation	216/13	257/E23.15	Daubenspeck, Timothy H. et al.
US 20030168714 A1	20030911	Triple damascene fuse	257/529	257/E23.149; 257/E23.167	Daubenspeck, Timothy H. et al.
US 20030156289 A1	20030821	Laser alignment target and method	356/401		Daubenspeck, Timothy H. et al.
US 20030116820 A1	20030626	Post-fuse blow corrosion prevention structure for copper fuses	257/529	257/E21.579; 257/E21.584; 257/E21.585; 257/E23.15; 438/132	Daubenspeck, Timothy H. et al.
US 20020182837 A1	20021205	Antifuse for use with low kappa dielectric foam insulators	438/601	257/E23.148; 257/E23.167; 438/132; 438/215; 438/281; 438/333; 438/467	Daubenspeck, Timothy H. et al.
US 20020146151 A1	20021010	System and method for automated fringe counting using image information	382/106		Huston, Dryver R. et al.
US 20020102475 A1	20020801	Method of curing a photosensitive material using evanescent wave energy	430/5	430/270.1; 430/321; 430/394	Esser, Brian et al.
US 20020066311 A1	20020606	Stiction-based chuck for bulge tester and method	73/159		Huston, Dryver R. et al.

		of bulge testing			
US 20010034084 A1	20011025	METHOD FOR MAKING A PEDESTAL FUSE	438/132	257/E23.15	Bouldin, Dennis P. et al.
US 20010031516 A1	20011018	Pedestal fuse	438/132	257/529; 257/E23.15	Bouldin, Dennis P. et al.
US 20010014509 A1	20010816	Method and structure for a semiconductor fuse	438/381	257/E23.15	Daubenspeck, Timothy Harrison et al.
US 7064409 B2	20060620	Structure and programming of laser fuse	257/529	257/209; 257/665; 257/E23.146; 257/E23.148; 257/E23.15	Badami; Dinesh A. et al.
US 7025891 B2	20060411	Method of polishing C4 molybdenum masks to remove molybdenum peaks	216/12	257/E21.304	Codding; Steven R. et al.
US 6995475 B2	20060207	I/C chip suitable for wire bonding	257/784	257/737; 257/761; 257/766; 257/E23.02	Biggs; Julie C. et al.
US 6991971 B2	20060131	Method for fabricating a triple damascene fuse	438/132	257/529; 257/E23.149; 257/E23.167; 438/215; 438/281; 438/333	Daubenspeck; Timothy H. et al.
US 6946379 B2	20050920	Insulative cap for laser fusing	438/601	257/E23.15; 257/E23.179; 438/132; 438/540	Daubenspeck; Timothy H. et al.
US 6924210 B1	20050802	Chip dicing	438/460	257/E21.599; 438/458; 438/462	Daubenspeck; Timothy H. et al.
US 6876058 B1	20050405	Wiring protection element for laser deleted tungsten fuse	257/529	257/659; 257/E23.15; 438/132; 438/381	Motsiff; William T. et al.
US 6864578 B2	20050308	Internally reinforced bond pads	257/737	257/734; 257/738; 257/741; 257/E23.02	Angell; David et al.

US 6856397 B2	20050215	System and method for automated fringe counting using image information	356/450	356/4.09	Huston; Dryver R. et al.
US 6835973 B2	20041228	Antifuse for use with low .kappa. dielectric foam insulators	257/209	257/211; 257/758; 257/E23.148; 257/E23.167	Daubenspeck; Timothy H. et al.
US 6833720 B1	20041221	Electrical detection of dicing damage	324/763	257/E23.002; 324/765	Daubenspeck; Timothy H. et al.
US 6827868 B2	20041207	Thinning of fuse passivation after C4 formation	216/17	216/67; 216/72; 216/79; 257/E23.15; 438/281; 438/697; 438/720; 438/724	Daubenspeck; Timothy H. et al.
US 6815838 B2	20041109	Laser alignment target and method	257/797	257/752	Daubenspeck; Timothy H. et al.
US 6784516 B1	20040831	Insulative cap for laser fusing	257/529	257/665; 257/797; 257/E23.15; 257/E23.179	Daubenspeck; Timothy H. et al.
US 6746947 B2	20040608	Post-fuse blow corrosion prevention structure for copper fuses	438/601	257/E21.579; 257/E21.584; 257/E21.585; 257/E23.15; 438/132; 438/215; 438/281; 438/333; 438/687	Daubenspeck; Timothy H. et al.
US 6734047 B1	20040511	Thinning of fuse passivation after C4 formation	438/132	257/E23.15; 438/215; 438/281; 438/601; 438/661; 438/662	Daubenspeck; Timothy H. et al.
US 6667533 B2	20031223	Triple damascene fuse	257/529	257/296; 257/642; 257/643; 257/E23.149;	Daubenspeck; Timothy H. et al.

				257/E23.167; 438/132; 438/215; 438/281; 438/333	
US 6539790 B2	20030401	Stiction-based chuck for bulge tester and method of bulge testing	73/150A		Huston; Dryver R. et al.
US 6498385 B1	20021224	Post-fuse blow corrosion prevention structure for copper fuses	257/529	257/536; 257/537; 257/758; 257/762; 257/E21.579; 257/E21.584; 257/E21.585; 257/E23.15	Daubenspeck; Timothy H. et al.
US 6496053 B1	20021217	Corrosion insensitive fusible link using capacitance sensing for semiconductor devices	327/525	257/173; 257/516; 257/529; 257/530; 257/532; 257/665; 257/910; 257/E21.008; 257/E23.15; 361/628; 361/630; 438/132; 438/215; 438/467	Daubenspeck; Timothy et al.
US 6492207 B2	20021210	Method for making a pedestal fuse	438/132	257/E23.15	Bouldin; Dennis P. et al.
US 6458630 B1	20021001	Antifuse for use with low k dielectric foam insulators	438/131	257/E23.148; 257/E23.167; 438/600; 438/610; 438/781	Daubenspeck; Timothy H. et al.
US 6455914 B2	20020924	Pedestal fuse	257/529	257/536; 257/537; 257/752; 257/762; 257/E23.15	Bouldin; Dennis P. et al.
US 6440834 B2	20020827	Method and structure for a	438/601	257/529; 257/E23.15;	Daubenspeck; Timothy

		semiconductor fuse		438/132; 438/600	Harrison et al.
US 6426557 B1	20020730	Self-aligned last-metal C4 interconnection layer for Cu technologies	257/750	257/760; 257/761; 257/774; 257/E23.02	Daubenspeck; Timothy et al.
US 6375159 B2	20020423	High laser absorption copper fuse and method for making the same	257/529	257/762; 257/764; 257/E23.15	Daubenspeck; Timothy H. et al.
US 6261873 B1	20010717	Pedestal fuse	438/132	257/E23.15; 438/215; 438/281; 438/333	Bouldin; Dennis P. et al.
US 6249038 B1	20010619	Method and structure for a semiconductor fuse	257/529	257/209; 257/E23.15	Daubenspeck; Timothy Harrison et al.
US 5935763 A	19990810	Self-aligned pattern over a reflective layer	430/313	257/E21.507; 257/E21.577; 430/315	Caterer; Michael Dean et al.
US 5804464 A	19980908	Semiconductor chip kerf clear method for forming semiconductor chips and electronic module therefore	438/109	257/E21.705; 257/E25.013; 438/462	Beilstein, Jr.; Kenneth Edward et al.
US 5793103 A	19980811	Insulated cube with exposed wire lead	257/690	257/686; 257/692; 257/700; 257/773; 257/777; 257/E23.011; 257/E25.013	Daubenspeck; Timothy H. et al.
US 5670428 A	19970923	Semiconductor chip kerf clear method and resultant semiconductor chip and electronic module formed from the same	438/109	257/E21.705; 257/E25.013; 438/462	Beilstein, Jr.; Kenneth Edward et al.
US 5644162	19970701	Semiconductor	257/690	257/685;	Beilstein, Jr.;

A		chip having chip metal layer and transfer metal layer composed of same metal, and corresponding electronic module		257/686; 257/700; 257/723; 257/735; 257/736; 257/758; 257/774; 257/E21.705; 257/E25.013	Kenneth Edward et al.
US 5609772 A	19970311	Cube maskless lead open process using chemical mechanical polish/lead-tip expose process	438/109	216/16; 216/72; 257/E21.705; 257/E25.013; 438/693; 438/694; 438/703	Daubenspeck; Timothy H. et al.
US 5596226 A	19970121	Semiconductor chip having a chip metal layer and a transfer metal and corresponding electronic module	257/690	257/692; 257/700; 257/723; 257/777; 257/E21.705; 257/E25.013	Beilstein, Jr.; Kenneth E. et al.
US 5219788 A	19930615	Bilayer metallization cap for photolithography	438/636	430/272.1; 430/318; 438/702; 438/720; 438/902; 438/950; 438/952	Abernathay; John R. et al.
US 4858287 A	19890822	Method for the continuous sizing and stretching of synthetic filament yarns	28/172.1	28/180; 28/246	Maurer; Peter et al.
US 4836887 A	19890606	Chlorofluorocarbon additives for enhancing etch rates in fluorinated halocarbon/oxidant plasmas	216/72	216/58; 216/75; 252/79.1; 257/E21.218; 257/E21.311	Daubenspeck; Timothy H. et al.
US 4836886 A	19890606	Binary chlorofluorocarbon chemistry for plasma etching	216/67	216/75; 252/79.1; 257/E21.218; 257/E21.311; 257/E21.312	Daubenspeck; Timothy H.